

Title (en)
PROCESS FOR HOT ROLLING AND FOR HEAT TREATMENT OF A STEEL STRIP

Title (de)
VERFAHREN ZUM WARMWALZEN UND ZUR WÄRMEBEHANDLUNG EINES BANDES AUS STAHL

Title (fr)
PROCÉDÉ DE LAMINAGE À CHAUD ET DE TRAITEMENT THERMIQUE D'UNE BANDE EN ACIER

Publication
EP 2162557 B1 20110406 (DE)

Application
EP 08758994 A 20080604

Priority
• EP 2008004435 W 20080604
• DE 102007029280 A 20070622
• DE 102008010062 A 20080220

Abstract (en)
[origin: US2010175452A1] The invention relates to a process for hot rolling and for heat treatment of a strip (1) of steel. To make it possible to produce high-strength and very high-strength strips having satisfactory toughnesses more economically in a continuous production plant, the process provides the steps: a) heating of the slab to be rolled; b) rolling of the slab to the desired strip thickness; c) cooling of the strip (1), with the strip (1) having a temperature above ambient temperature (T0) after cooling; d) rolling up of the strip (1) to produce a coil (2); e) rolling off of the strip (1) from the coil (2); f) heating of the strip (1); g) cooling of the strip (1) and h) transport of the strip (1) to a further destination, with the strip (1) having a temperature above ambient temperature (T0) before heating as per step T).

IPC 8 full level
C21D 8/02 (2006.01); **B21B 1/26** (2006.01); **C21D 8/04** (2006.01); **C21D 9/46** (2006.01); **C21D 9/48** (2006.01)

CPC (source: EP KR US)
B21B 1/26 (2013.01 - KR); **C21D 8/0226** (2013.01 - EP US); **C21D 8/0252** (2013.01 - EP US); **C21D 8/0263** (2013.01 - EP US); **C21D 8/04** (2013.01 - KR); **C21D 8/0426** (2013.01 - EP US); **C21D 8/0452** (2013.01 - EP US); **C21D 8/0463** (2013.01 - EP US); **C21D 9/46** (2013.01 - EP US); **C21D 9/48** (2013.01 - EP KR US); **B21B 1/26** (2013.01 - EP US)

Citation (examination)
• JP S58122107 A 19830720 - HITACHI LTD
• DE 4041206 A1 19920625 - SCHLOEMANN SIEMAG AG [DE]
• EP 1317325 B1 20050817 - SIEMENS AG [DE]

Cited by
CN110616299A

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)
US 2010175452 A1 20100715; AR 067091 A1 20090930; AT E504665 T1 20110415; AU 2008267505 A1 20081231; AU 2008267505 B2 20101125; BR PI0812324 A2 20141125; CA 2686377 A1 20081231; CA 2686377 C 20110927; CN 101755058 A 20100623; CN 101755058 B 20111109; DE 102008010062 A1 20081224; DE 502008003118 D1 20110519; DK 2162557 T3 20110711; EG 25307 A 20111207; EP 2162557 A1 20100317; EP 2162557 B1 20110406; ES 2362052 T3 20110627; JP 2010530807 A 20100916; JP 5485147 B2 20140507; KR 101153732 B1 20120614; KR 20100007940 A 20100122; MX 2009013530 A 20100127; MY 148425 A 20130430; PL 2162557 T3 20110930; RU 2010101900 A 20110727; RU 2429922 C1 20110927; SI 2162557 T1 20110831; TW 200914157 A 20090401; TW I412410 B 20131021; UA 98653 C2 20120611; WO 2009000387 A1 20081231; ZA 200907733 B 20100630

DOCDB simple family (application)
US 60227708 A 20080604; AR P080102646 A 20080620; AT 08758994 T 20080604; AU 2008267505 A 20080604; BR PI0812324 A 20080604; CA 2686377 A 20080604; CN 200880021446 A 20080604; DE 102008010062 A 20080220; DE 502008003118 T 20080604; DK 08758994 T 20080604; EG 2009121765 A 20091206; EP 08758994 A 20080604; EP 2008004435 W 20080604; ES 08758994 T 20080604; JP 2010512554 A 20080604; KR 20097024981 A 20080604; MX 2009013530 A 20080604; MY PI20095263 A 20080604; PL 08758994 T 20080604; RU 2010101900 A 20080604; SI 200830299 T 20080604; TW 97120680 A 20080604; UA A201000592 A 20080604; ZA 200907733 A 20091104